



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD90N10S4L-06		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000939132						
<b>Package</b>		PG-TO252-3-313		<b>Weight*</b>		319.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.429	1.38	1.38	13845	13845
leadframe	non noble metal	iron	7439-89-6	0.166	0.05		520	
	inorganic material	phosphorus	7723-14-0	0.050	0.02		156	
	non noble metal	copper	7440-50-8	166.274	51.99	52.06	519807	520483
wire	non noble metal	aluminium	7429-90-5	4.357	1.36	1.36	13620	13620
encapsulation	organic material	carbon black	1333-86-4	1.360	0.43		4252	
	plastics	epoxy resin	-	23.801	7.44		74408	
	inorganic material	silicondioxide	60676-86-0	110.846	34.65	42.52	346530	425190
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11692	11692
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4441	4452
solder	noble metal	silver	7440-22-4	0.086	0.03		268	
	non noble metal	tin	7440-31-5	0.069	0.02		214	
	non noble metal	lead	7439-92-1	3.274	1.02	1.07	10236	10718
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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